TIGER ASIC for GEM Readout

RD51 Topical Workshop on
FE electronics for gas detectors
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Istituto Nazionale di Fisica Nucleare

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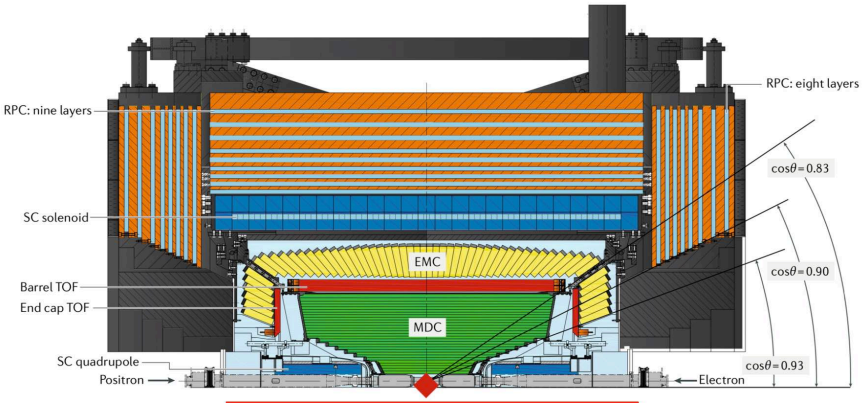
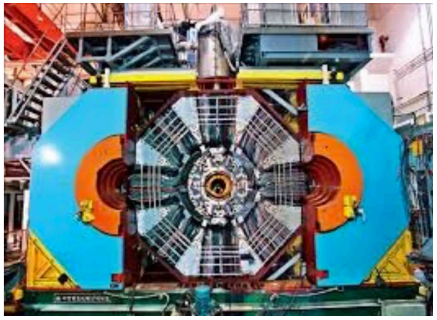
The BESIIICGEM project has been funded by European Commission within the calls
H2020-MSCA-RISE-2014 and FEST RISE-MSCA-H2020-2020

The BESIII Experiment at BEPCII

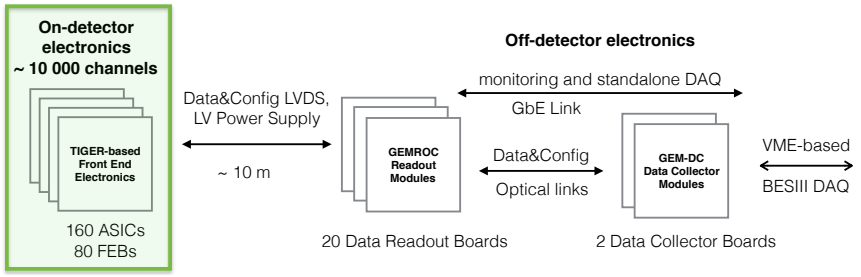
- The BESIII experiment @ BEPCII (Beijing Electron-Positron Collider) - operation since 1989, upgrade to BEPCII in 2008
- BESIII Collaboration counts ~500 authors from 67 Institutions, 14 Countries

Parameters	BEPCII
Center of mass Energy	$(2.0 \div 4.6)$ GeV
Peak luminosity at 2×1.89 GeV	$\sim 10^{33}$ cm^{-2} s^{-1}
Circumference	237.5 m
Number of rings	2
RF frequency	499.8 MHz
Number of bunches	2×93
Beam current	2×0.91 A
Bunch spacing	2.4/8 m ns^{-1}
Bunch length (σ_z)	1.5 cm
Bunch width (σ_x)	~ 380 μm
Bunch height (σ_y)	~ 5.7 μm



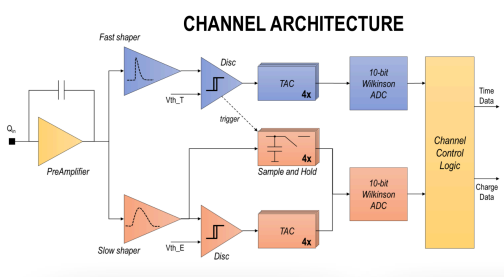


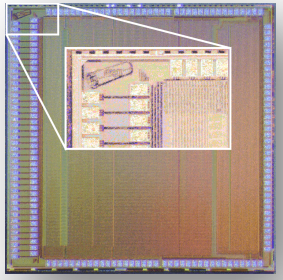
- new lightweight tracker based on an innovative Cylindrical Gas Electron Multiplier (CGEM) detector for the upgrade of the BESIII spectrometer
- analogue readout of the CGEM enables the use of charge centroid and μ-TPC algorithms to improve the spatial resolution
- 10 000 channels are readout by 160 dedicated 64-channel front-end ASICs

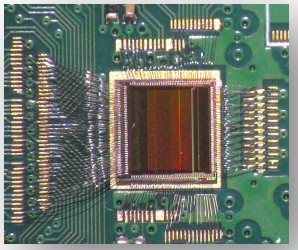


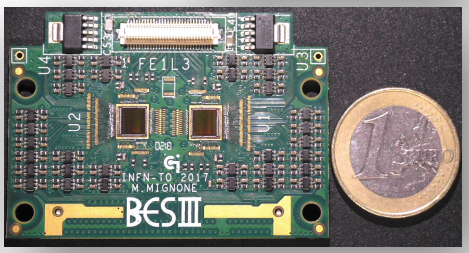
Upgrade of the BESIII Inner Tracker

- Spatial resolution: σ_{xy} = 130 μm , σ_z= 300 μm
- Momentum resolution: σ_{pt}/p_t = 0.5% @ 1 GeV/c
- Efficiency = 98%
- Material budget ≤ 1.5% of X_0 for all layers
- Rate capability: ~10^4 Hz/cm^2
- Coverage: 93% 4π



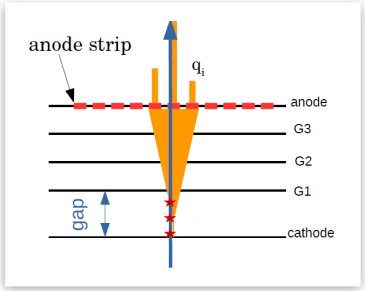






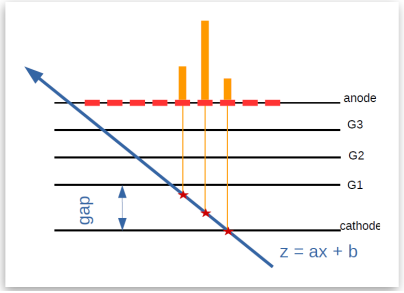
Reconstruction algorithms

Charge Centroid



Weighted average of strip positions by collected charge

μ-TPC readout



2D track reconstruction exploiting time of arrival and

TIGER ASIC for the CGEM-IT Readout

- provides an analogue readout (time and charge information) for CC and μ-TPC algorithms
- 64-channel **A**pplication **S**pecific **I**ntegrated **C**ircuit

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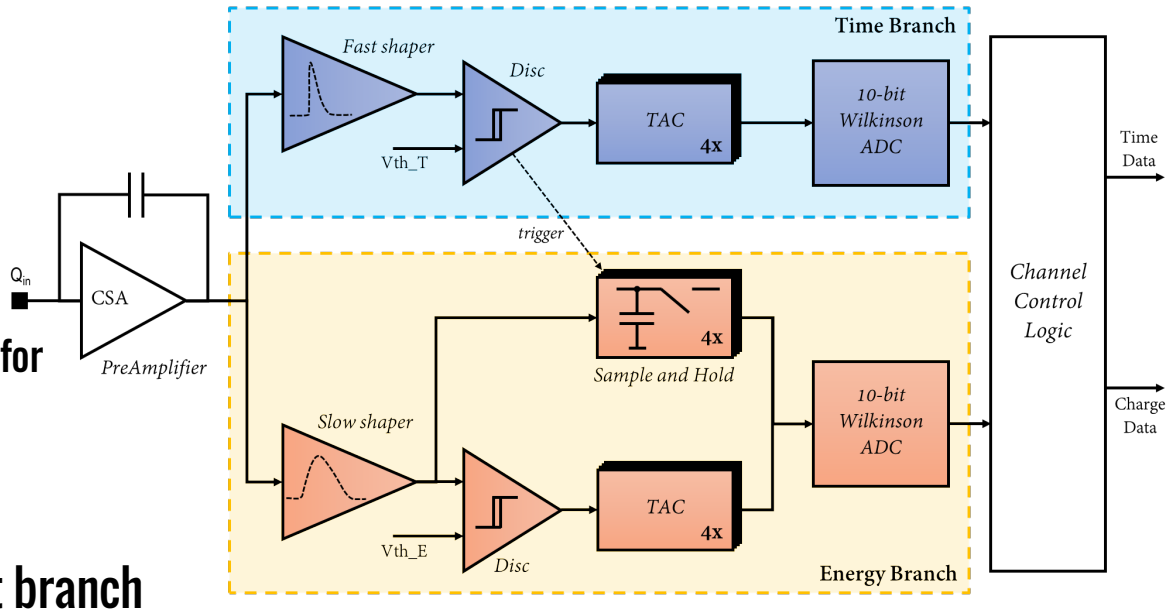
TIGER ASIC for the BESIII CGEM-IT

- TIGER has been designed for the readout of the **CGEM-IT** (Cylindrical Gas Electron Multiplier Inner Tracker)
  - new inner tracker of BESIII Experiment
  - **10 000 channels** readout by 160 **64-channel TIGER ASICs**
- **Time** and **charge** measurements with fully-digital output
  - **Charge centroid** and **μ-TPC** algorithms
  - 130 μm spatial resolution with strip pitch of 650 μm
- Sensor capacitance dependent on strips length, up to **100 pF**
- Input charge: **2 - 50 fC**
- Time resolution for μTPC mode: **5 ns**
- Rate per channel: **60 kHz** (4x safety factor)
- Power consumption: **< 12 mW/ch**
- SEU-tolerant

Efficiency	98%
Rate capability	10 kHz/cm^2
$\sigma_{r\Phi}$	130 μm
σ_z	300 μm
σ_{pt}/p_t	0.5% at 1 GeV/c
Coverage	93% 4π
Material budget	< 1.5 X_0
Inner radius	78 mm
Outer radius	178 mm
Magnetic field	1 T

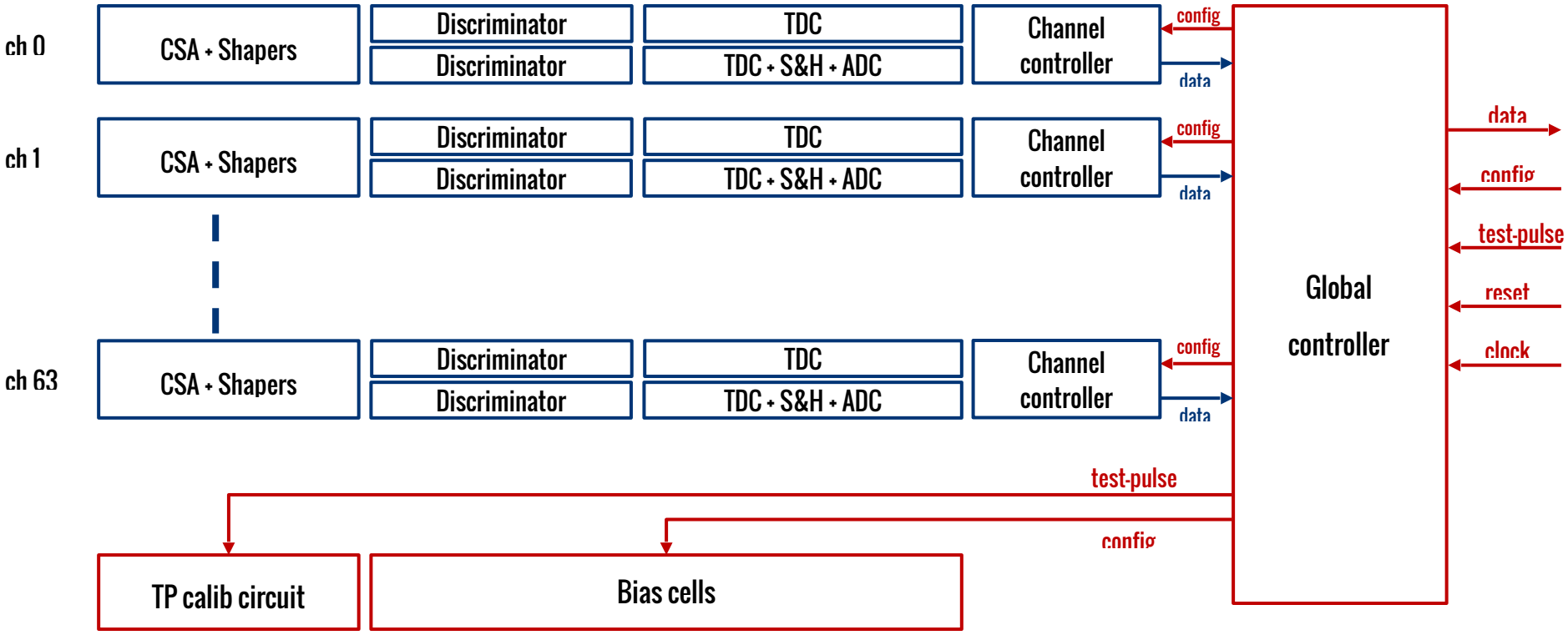
Channel Architecture

- Analogue Front-End:
  - **Charge Sensitive Amplifier**
  - **dual-branch** shaper optimized for time and charge measurements
- **Trigger-less** readout architecture:
  - 2 LE discriminators with 6-bit DAC for threshold equalization
  - dual-threshold readout mode
- **Timestamp** on rising edge of fast branch
  - Time resolution < 5 ns
  - Low-power TDCs based on analogue interpolation
- **Charge** measurement:
  - ToT: timestamp on rising/falling edge
  - S/H: slow shaper output sampled and digitized with a 10-bit Wilkinson ADC



ASIC Architecture

- The ASIC embeds an array of 64 channels (amplifier, discriminator, TDC/ADC), a digital global controller, bias and references generators and a test-pulse calibration circuit.



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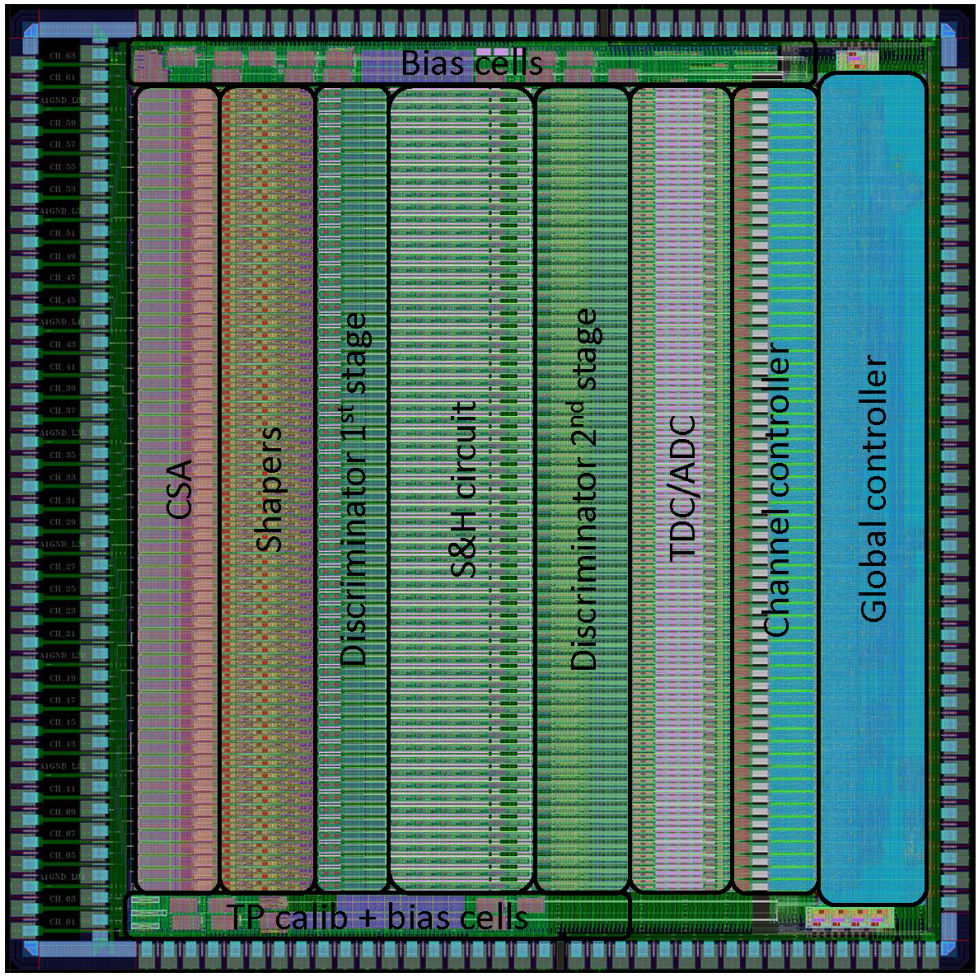
Chip Floorplan

- 5 x 5 mm^2 110nm CMOS technology
- Digital backend adapted from **TOFPET2*** (SEU protected)
- **64 channels**: CSA, shapers, TDC/ADC, local controller
- On-chip bias and power management
- On-chip calibration circuitry
- **Trigger-less** operation, fully digital output
- 160-200 MHz system clock
- 4 TX SDR/DDR LVDS links, 8B/10B encoding
- 10 MHz SPI-like configuration link
- Sustained event rate > **100 kHz/ch**



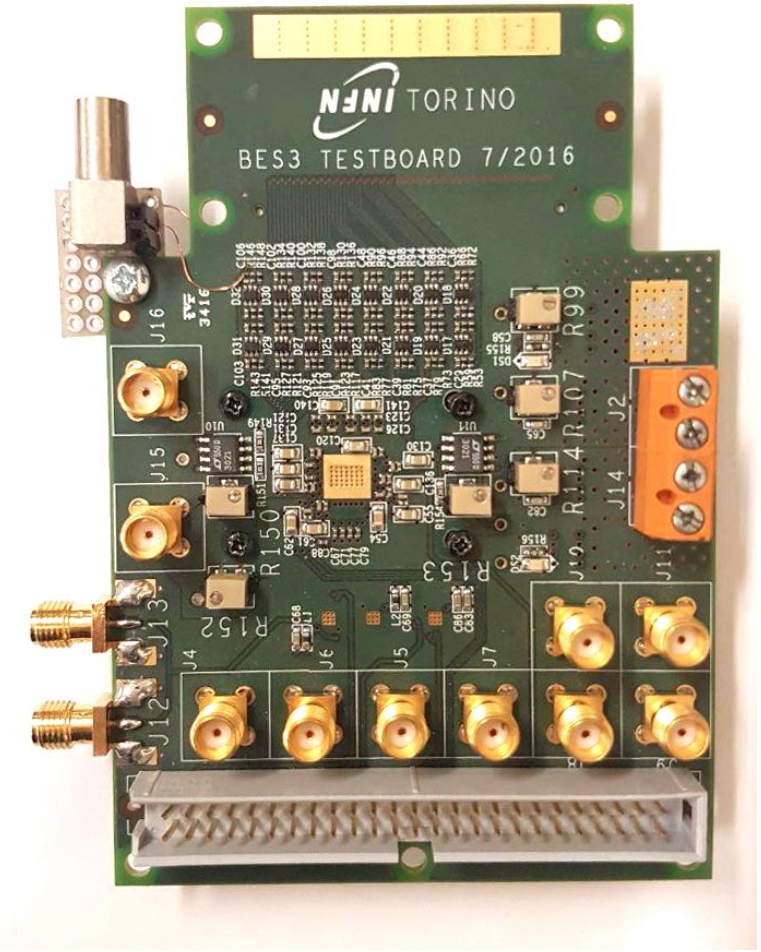
*https://doi.org/10.1088/1748-0221/14/03/P03029

Chip Test Board

Test-board for ASIC electrical characterization

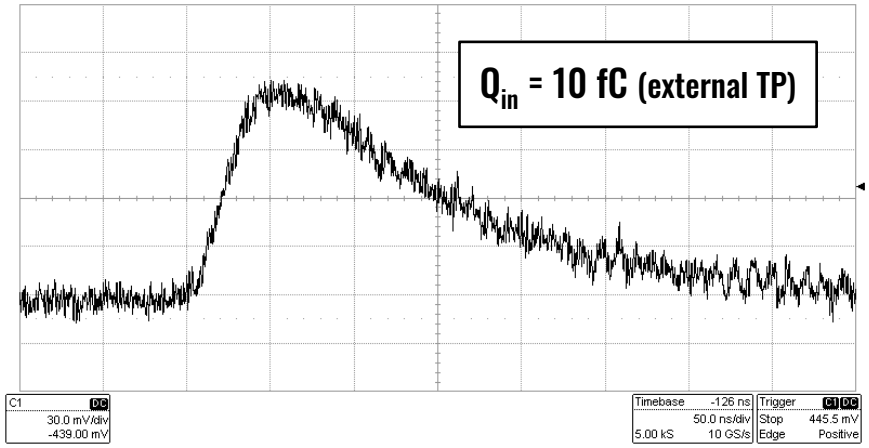
- Trimming capability for analogue and digital power domains and external reference voltages

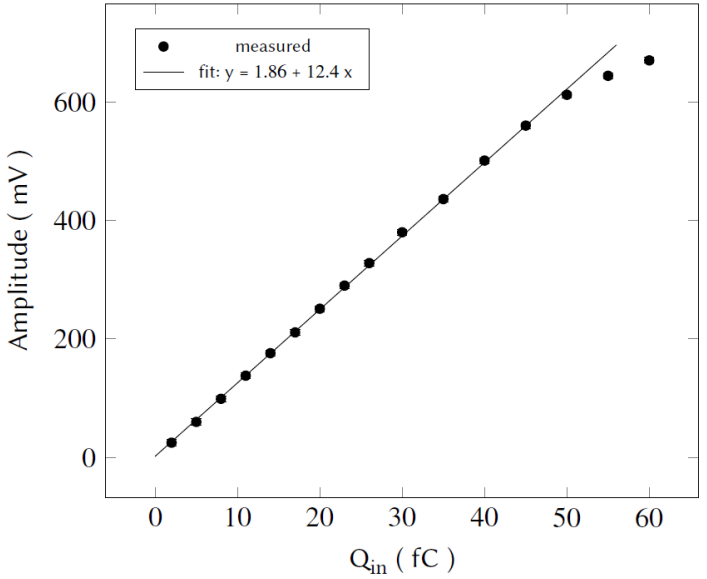
- **Debug IO ports:**
  2. External test-pulse injection
  3. External capacitor insertion
  4. T-branch shaper output and threshold probe points (ch. 63)
  5. Digital back-end control signals (TDC and S&H)



Electrical Characterization

Front-end response and linearity





ΔV ≈ 120 mV

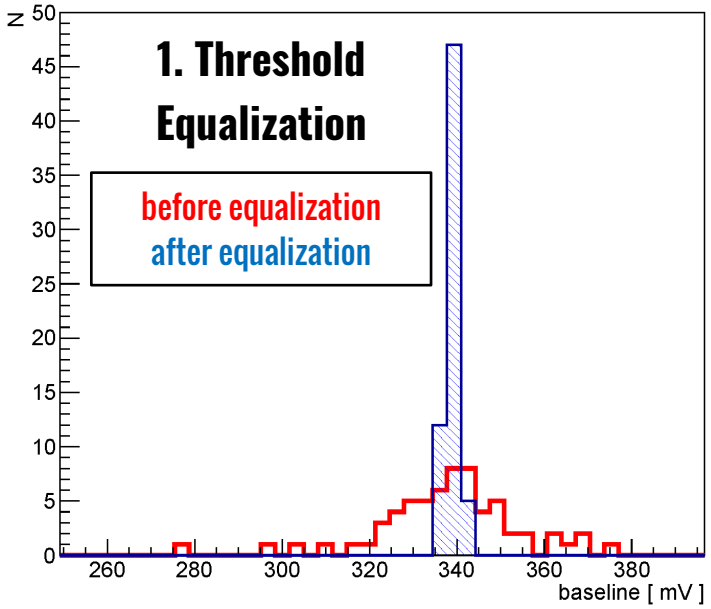
Peaking time ≈ 60 ns

Gain ≈ 12.4 mV/fC

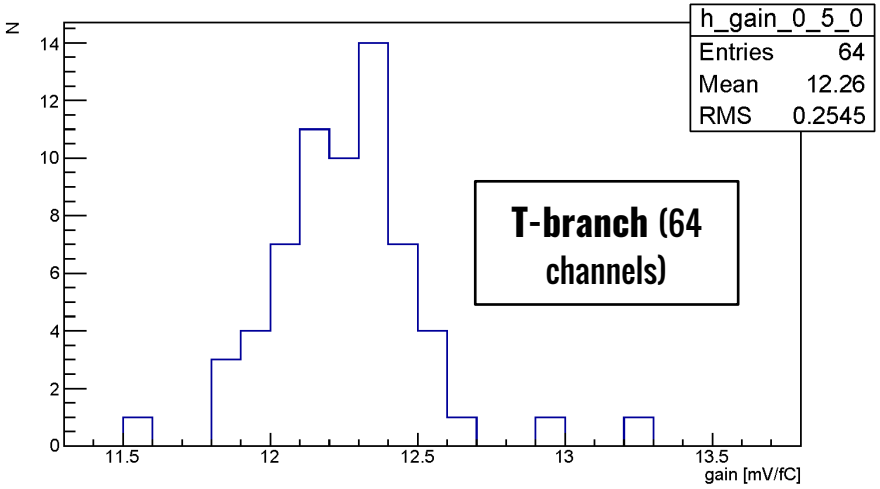
Electrical Characterization

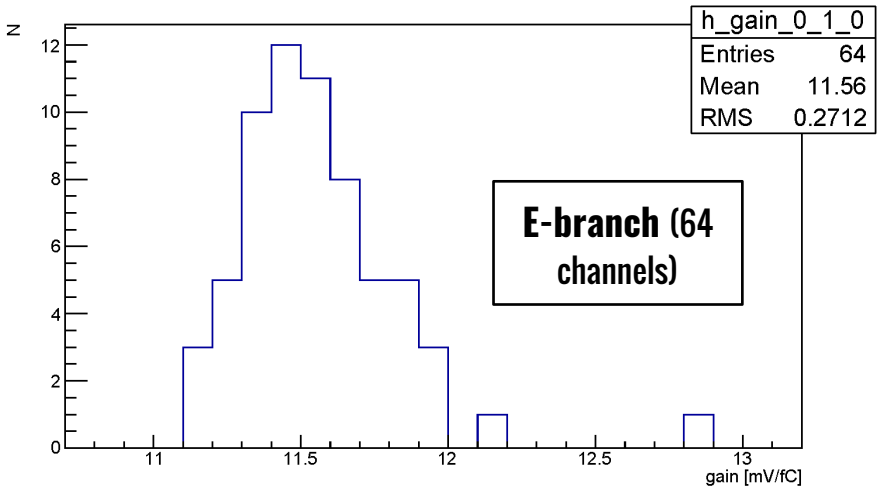
Threshold scan and gain dispersion

1. V_{th} scan to generate LUT and equalize thresholds
   - ➢ below 5 mV RMS dispersion after V_{th} equalization
2. V_{th} scan with internal TP to measure gain of 64 channels on both branches



2. Gain dispersion



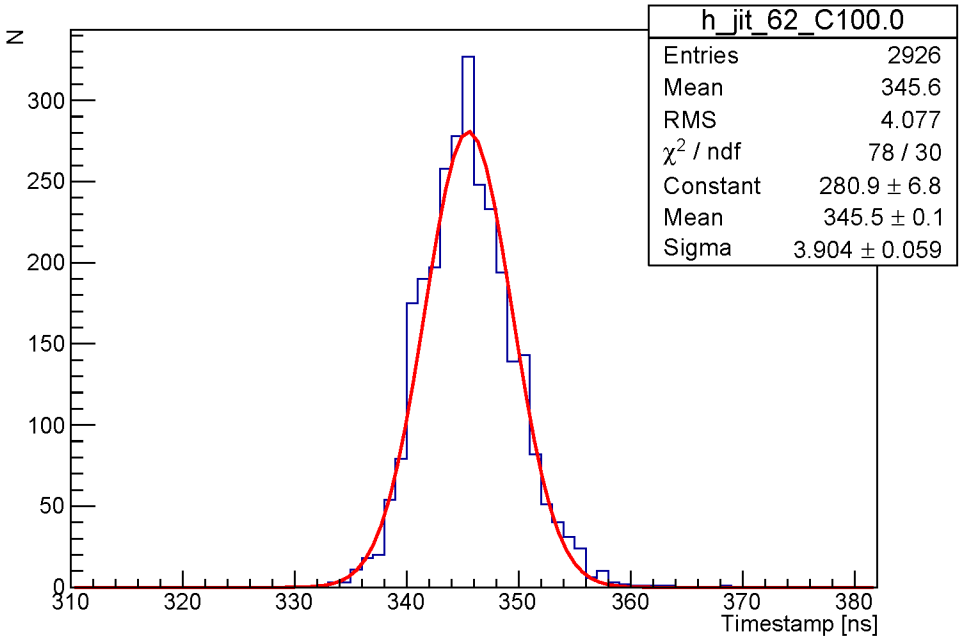


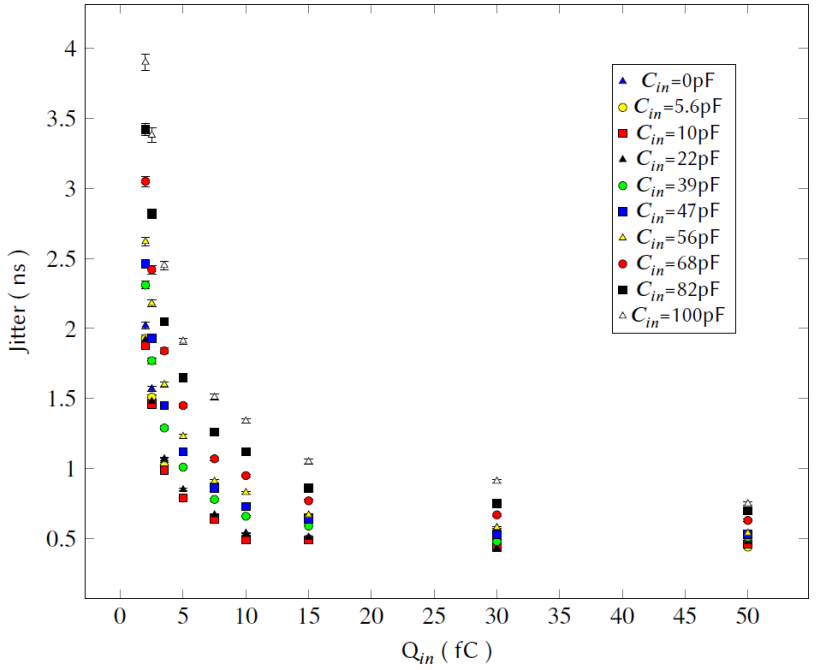
Electrical Characterization

Timing Resolution

- TP injected to VFE, generated by on-chip calibration circuit
- Here, fixed amplitude and time skew in respect to system clock

- Jitter vs. Q_{in} vs. C_{in}

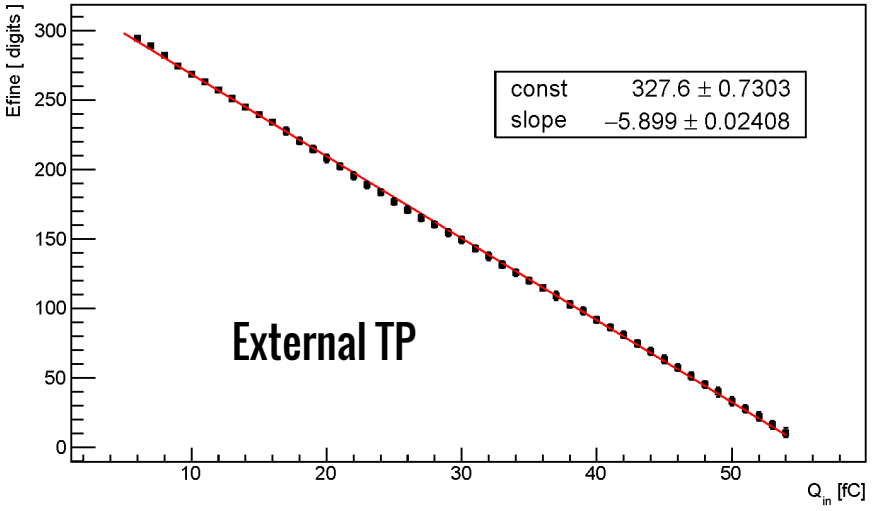


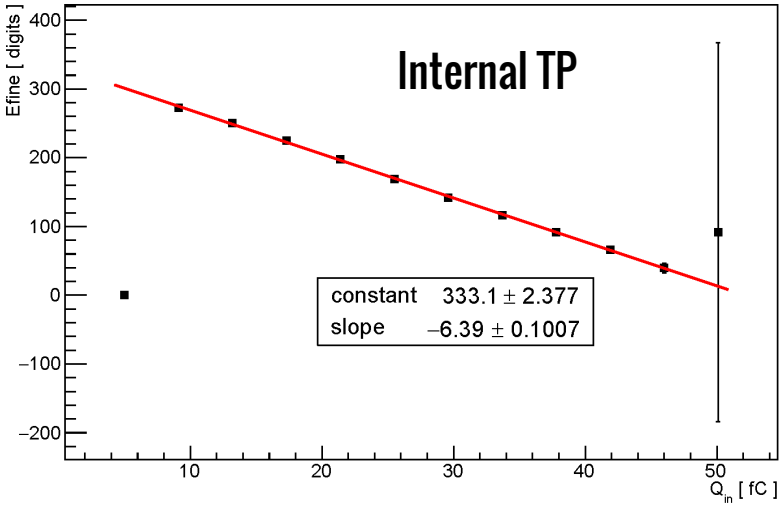


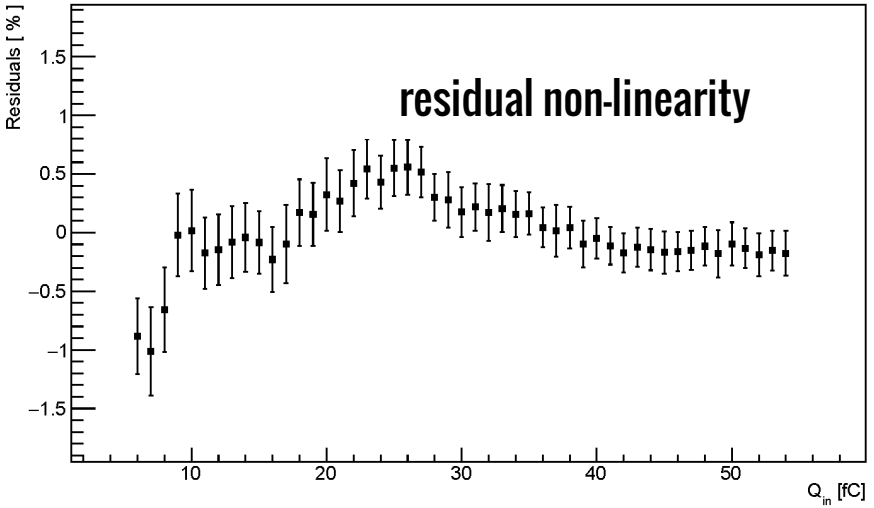
Electrical Characterization

Charge Measurement

- S/H **dynamic range** and **linearity** with external test-pulse generator (ch. 63 input debug port)
- Back-annotation for **internal test pulse calibration** to assess all channels



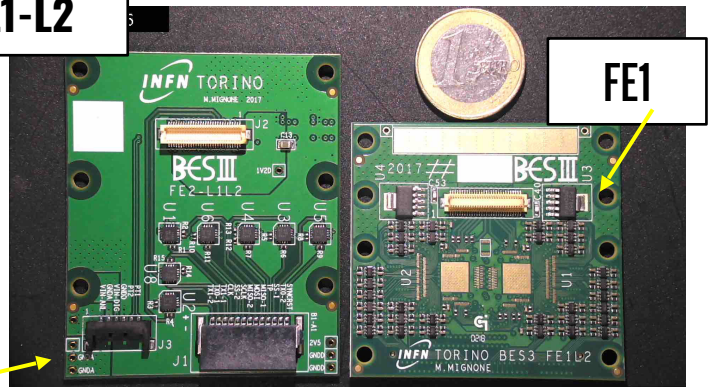


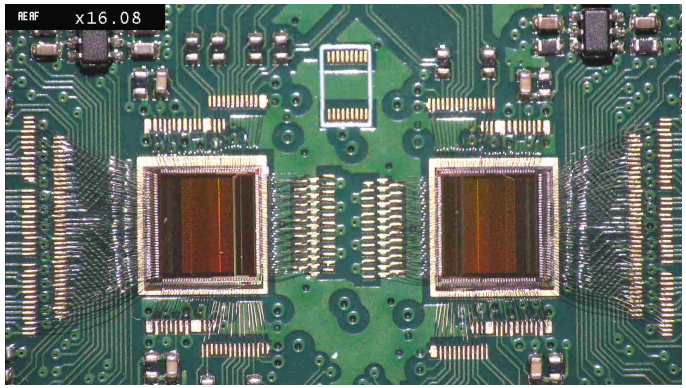


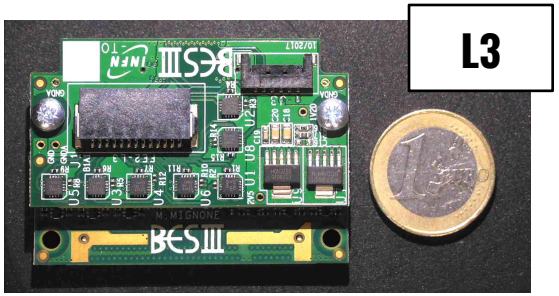
FEB (Front-End Board)

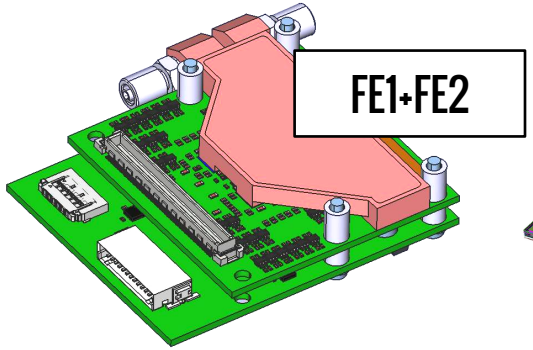
Front-End Board (FEB) for the on-detector CGEM electronics

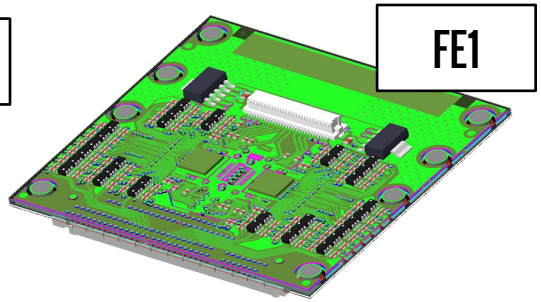
- Stack of two printed circuit boards:
  - ➢ FE1: analogue-most layer
  - ➢ FE2: digital layer
- 2 TIGER ASICs mounted on FE1 (128 channels per FEB)
- **Water-cooling heat exchanger plate** for operation at controlled temperature
- Different layout and routing for L3 FEBs due to space constraints inside BESIII



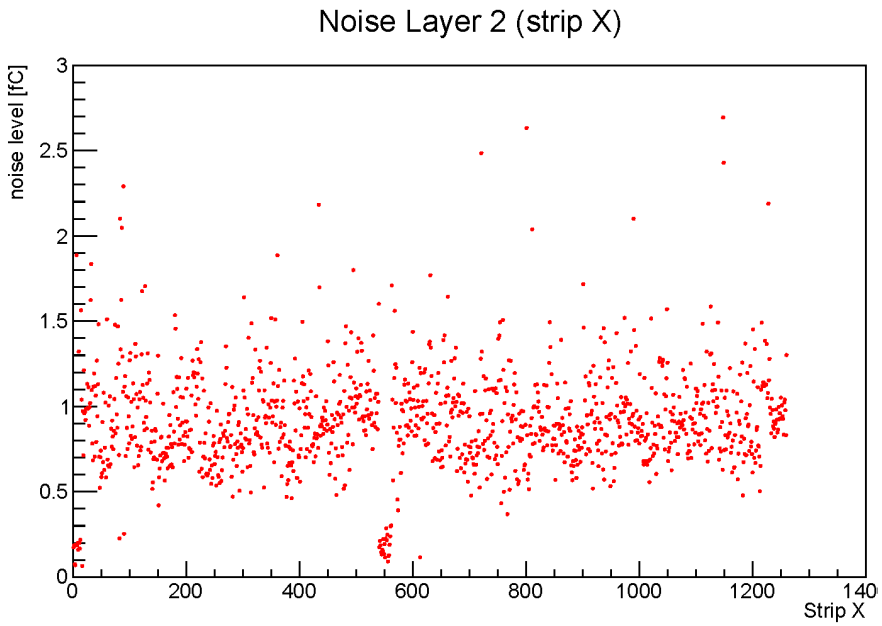


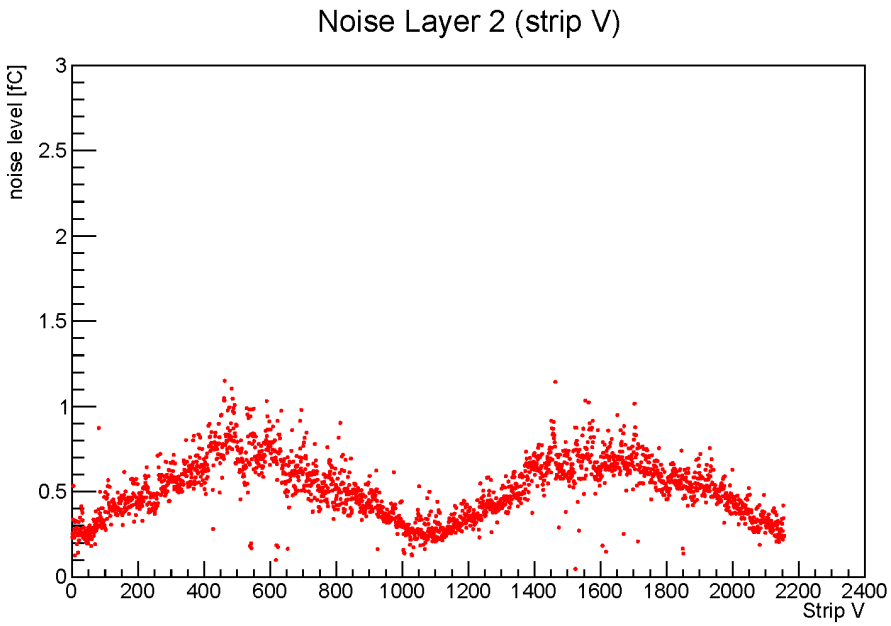




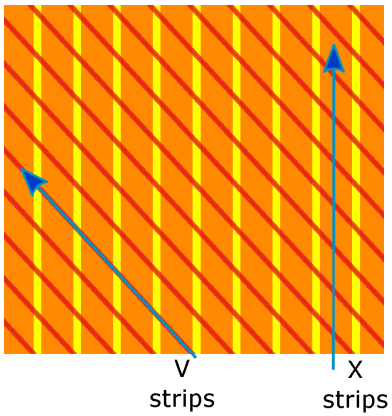


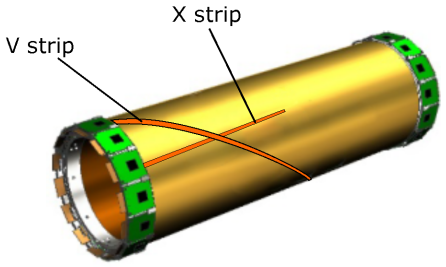
Noise measurements on CGEM





- Almost flat distribution for **X-strips**
- **V-strips** noise follows the strips length

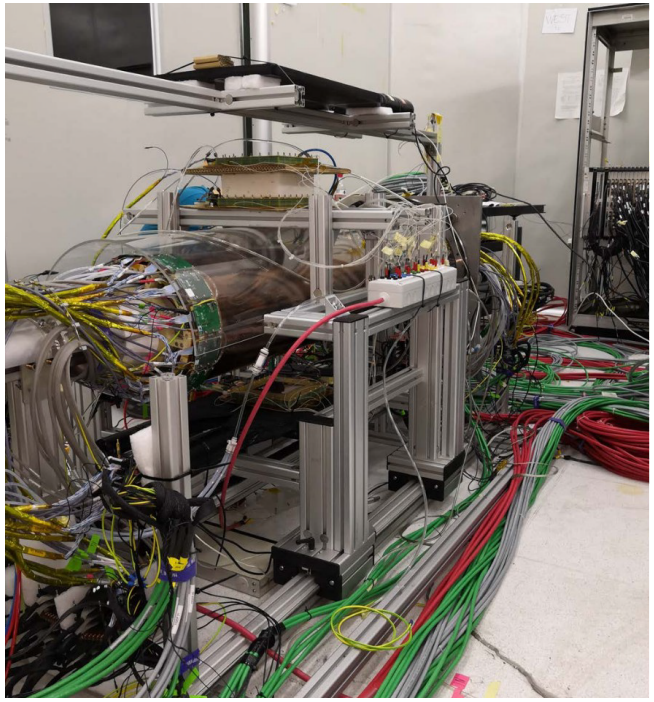


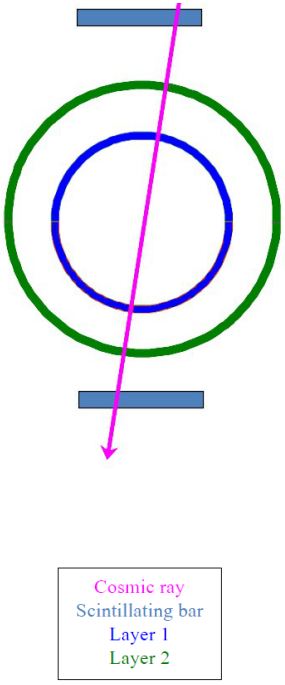


CGEM-IT commissioning

Two out of three layers of the CGEM-IT detector are assembled together and cosmic rays acquisitions are now ongoing at IHEP (Beijing, China)

- 88 TIGER ASICs readout by 11 GEMROC modules (**>5000 electronics channels** instrumented)
- GUFI (Graphical User Front-end Interface) software provides DAQ control tools for:
  - Trigger-matched cosmic acquisition
  - Trigger-less operation for periodic maintenance





R. Farinelli et al 2020 JINST 15 C08004 "Preliminary results from the cosmic data taking of the BESIII cylindrical GEM detectors"

Thanks for your attention.

Istituto Nazionale di Fisica Nucleare

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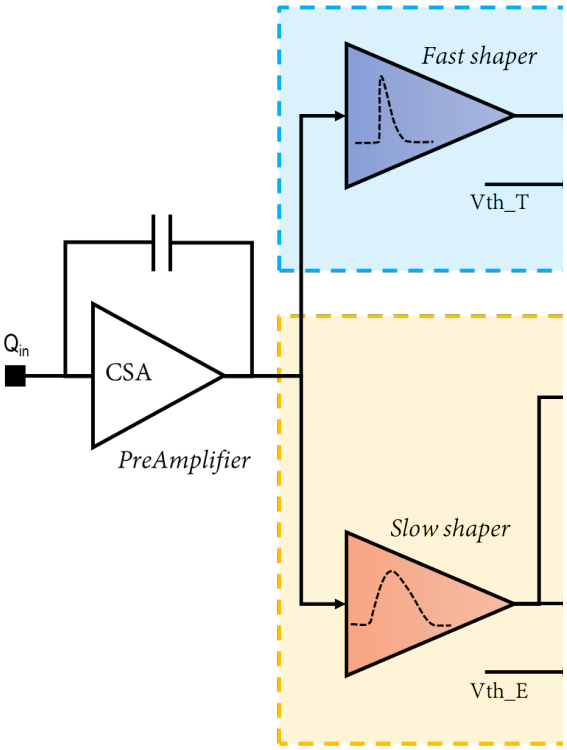
HORIZON 2020 European Commission

Analog Front-End



1. **CSA pre-amplifier**
   - Q_{in} = 2 - 50 fC
   - input transistor bias current set by 6-bit DAC (1.5 - 4.5 mA)
   - ENC target < 2000 e^- @ C_{in} = 100 pF
2. **Time-branch**
   - Simple CR-RC shaper
   - 60 ns peaking time for low-jitter timing measurement
3. **Energy-branch**
   - 4 complex-conjugate poles shaper for a more gaussian signal shape to reduce pile-up probability
   - 170 ns peaking time for signal-to-noise ratio optimization

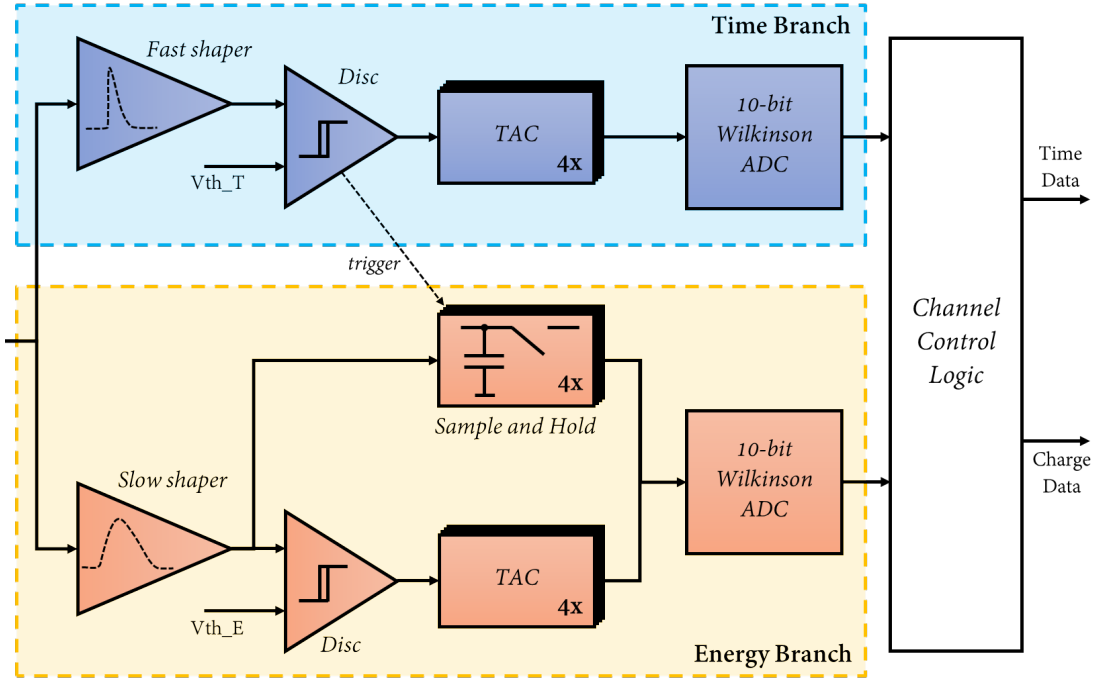
- **BLH** to lock the shapers output DC to an external reference value (V_{BL} = 350 mV)

➢ Total gain ≈ 12 mV/fC

Trigerless Readout

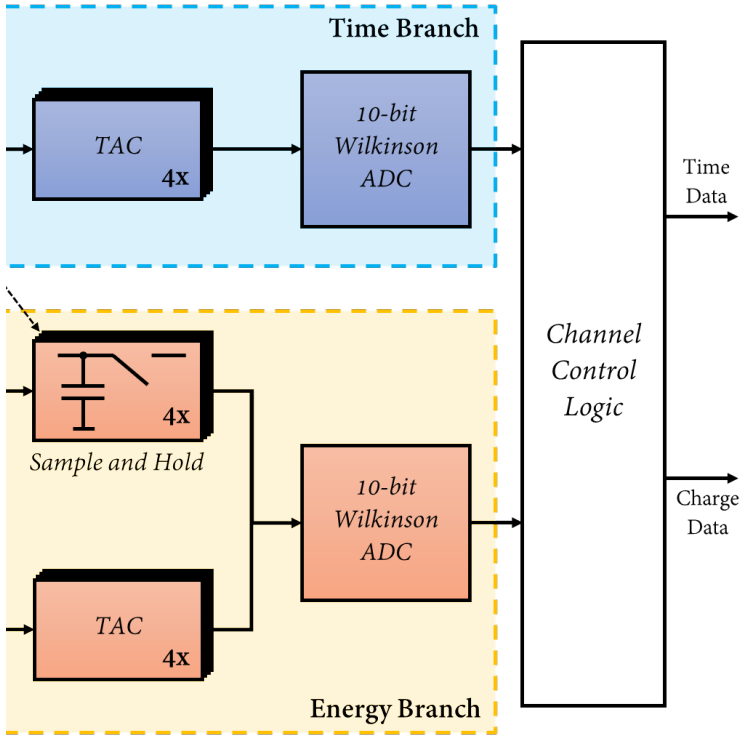
- **LE discriminators** with 6-bit DAC programmable thresholds and 3-bit DAC hysteresis

- **Data-push** readout architecture: each signal above the selected threshold is taken as a good event, digitized and sent off-chip (no external trigger)



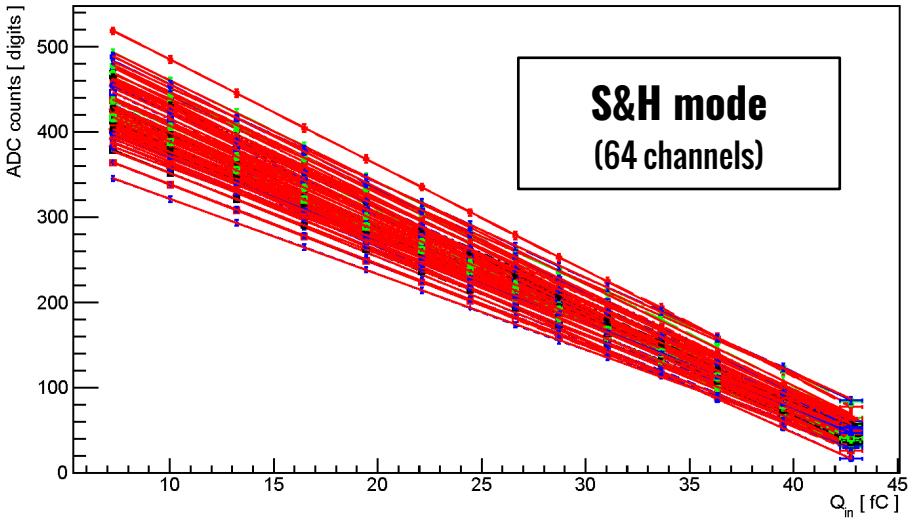
Time and Charge Measurement

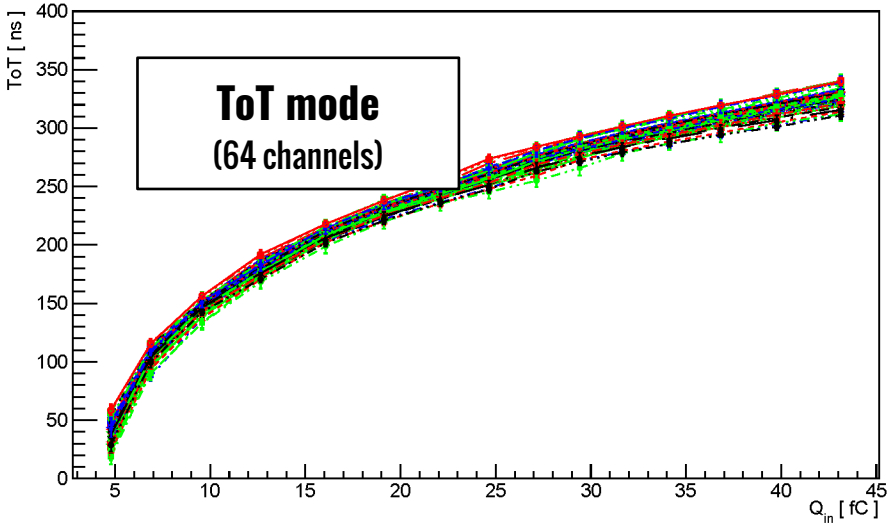
- **Coarse time measurement** from the chip master clock counter
- **Fine time measurement** with low-power analogue TDCs based on time interpolation (I.F. = 128)
  - 50 ps time binning @ 160 MHz
  - Quad-buffered TACs for **event de-randomization**
  - TAC buffers with refresh scheme to avoid off-chip correction algorithm for leakage
- **Charge measurement** with S/H circuit sampling the E-branch shaper output
  - Programmable sampling time targeting the **signal peak**
  - Digitization with **Wilkinson ADC** shared with the TDC
  - Quad-buffered sampling capacitors for **event de-randomization**
- **Charge measurement** from ToT information by operating both branches in TDC mode (backup solution)



Electrical Characterization

Charge Measurement





- **Linear response** from S&H circuit - easy to calibrate
- S&H limited by **saturation** of FE and ADC above 50 fC
- ToT response intrinsically not linear with CR-RC shapers
- **ToT provides** moderate energy resolution at low Qin, allows for **extended dynamic range**